# **UNRF1AM**

## Silicon PNP epitaxial planar transistor

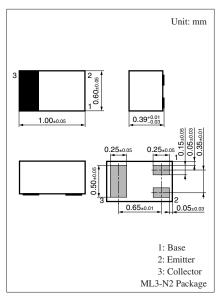
### For digital circuits

#### ■ Features

 Suitable for high density package and downsizing of the equipment for Ultraminiature leadless package
 0.6 mm × 1.0 mm (height 0.50 mm)

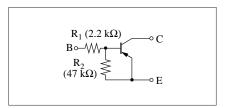
## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Rating	Collector to base voltage	$V_{CBO}$	V		
of	Collector to emitter voltage	V <sub>CEO</sub>	-50	V	
element	Collector current	$I_C$	-80	mA	
Overall	Total power dissipation	P <sub>T</sub>	100	mW	
	Junction temperature	T <sub>j</sub>	125	°C	
	Storage temperature	$T_{stg}$	-55 to +125	°C	



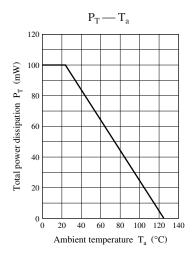
Marking Symbol: 1S

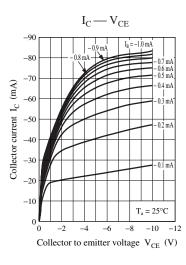
#### Internal Connection

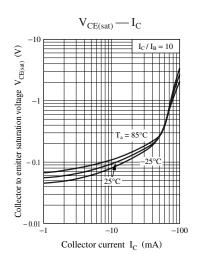


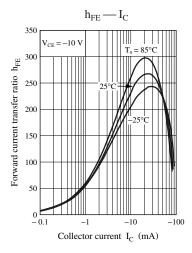
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

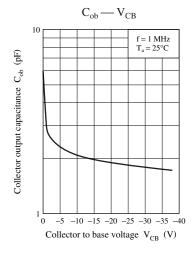
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector to base voltage	$V_{CBO}$	$I_C = -10 \ \mu A, I_E = 0$	-50			V
Collector to emitter voltage	V <sub>CEO</sub>	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Collector cutoff current	$I_{CBO}$	$V_{CB} = -50 \text{ V}, I_E = 0$			- 0.1	μΑ
	$I_{CEO}$	$V_{CE} = -50 \text{ V}, I_B = 0$			- 0.5	
Emitter cutoff current	$I_{EBO}$	$V_{EB} = -6 \text{ V}, I_C = 0$			- 0.2	mA
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	80			_
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -0.3 \text{ mA}$			- 0.25	V
High level output voltage	V <sub>OH</sub>	$V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	-4.9			V
Low level output voltage	V <sub>OL</sub>	$V_{CC} = -5 \text{ V}, V_B = -2.5 \text{ V}, R_L = 1 \text{ k}\Omega$			- 0.2	V
Input resistance	R <sub>1</sub>		-30%	2.2	+30%	kΩ
Resistance ratio	R <sub>1</sub> / R <sub>2</sub>			0.047		_
Gain bandwidth product	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

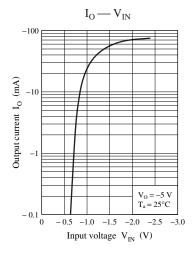


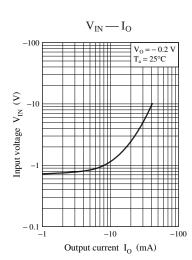












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